



Layer Stack Up Detail for: TINY-BLDC

Layer Name

Top Layer

BottomLayer

| Layer | Name | Material | Thickness | Constant | Board Layer Stack |
|-------|----------------|---------------|-----------|----------|-------------------|
| 1 | Top Paste | | | | |
| 2 | Top Overlay | | | | |
| 3 | Top Solder | Solder Resist | 0.40mil | 3.5 | |
| 4 | Top Layer | Copper | 1.40mil | | |
| 5 | Dielectric1 | FR-4 | 10.00mil | 4.2 | |
| 6 | Signal Layer 1 | Copper | 1.42mil | | |
| 7 | Dielectric 3 | | 5.00mil | 4.2 | |
| 8 | GND Plane | Copper | 1.42mil | | |
| 9 | Dielectric 2 | | 10.00mil | 4.2 | |
| 10 | Bottom Layer | Copper | 1.40mil | | |
| 11 | Bottom Solder | Solder Resist | 0.40mil | 3.5 | |
| 12 | Bottom Overlay | | | | |
| 13 | Bottom Paste | | | | |

